



# Product End-of-Life Disassembly Instructions

**Product Category:** Personal Computers

**Marketing Name / Model**  
 [List multiple models if applicable.]

HP TouchSmart 9100 Business PC

**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

## 1.0 Items Requiring Selective Treatment

- 1.1 Items listed below are classified as requiring selective treatment.
- 1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	10
Batteries	All types including standard alkaline and lithium coin or button style batteries	9
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	4
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers	0
Components, parts and materials containing radioactive substances	0

### 1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
M5 REAR FRAME A	rear frame	239.34	>ABS<	
M5 REAR PANEL	rear panel	354.16	>ABS<	
M5 FRONT BEZEL	bezel	161.75	>ABS<	
M5 CHIN	chin	124.1	>ABS<	
M5 REAR PANEL BTM	panel bottom	147.01	>ABS<	
M5 REAR FRAME B	rear frame	254	>ABS<	
M5 SIDE CAP LF	side cap left	26.17	>ABS<	
M5 SIDE CAP LF W/O Asklight_Btn	side cap left bottom	25.19	>ABS<	
M5 INNER BEZEL	inner bezel	78.02	>ABS<	
M5 IO DOOR	Input/ouput connector door	44.59	>ABS<	
STAND_TRIM	stand trim	52.15	>PMMA<	
STAND_COVER	stand cover	58.33	>ABS<	
Thermal Housing	fan housing	29.9g	> PET<	

## 2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1	
Description #2	
Description #3	
Description #4	
Description #5	

## 3.0 Product Disassembly Process

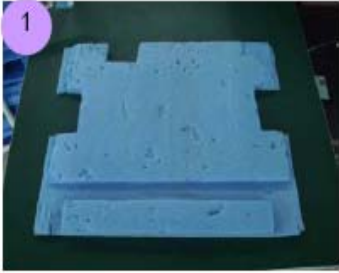
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

- 1.
- 2.
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

**Figure 1 : Mechanical parts disassembly**

1) Place the system



Put down unit on shuttle car and let stand upside

2) Dongle holder and I/O cover



Pull out dongle and put it into KB box

pull out the I/O plastic cover from

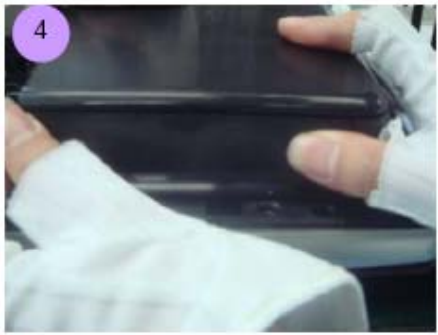
3) Trim and B-CAS, ODD cover



Disassembly right and left trim as pic shows



put trims into materila area

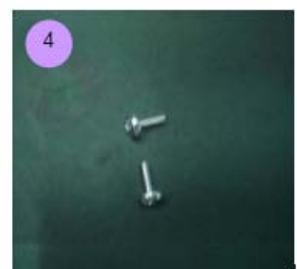
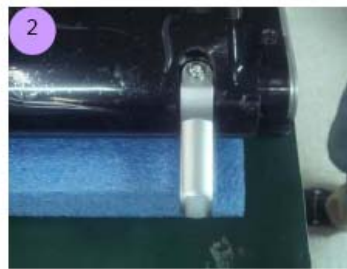


pull out B-CAS COVER

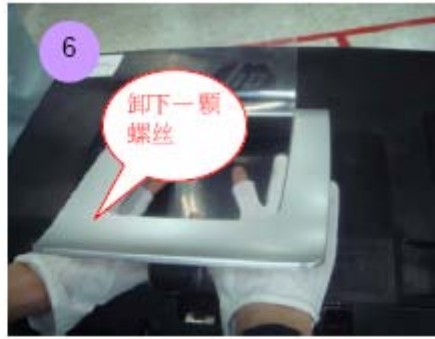


Disassembly ODD plastic cover

#### 4) Foot and rear cover



Disassemble screw on foot(Right & left side) with electrical screw driver and place it in material box.

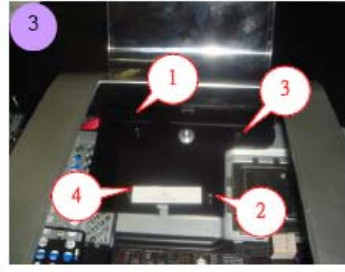


Losse screw on low rear cover and pull it off from unit

## 5) Stand



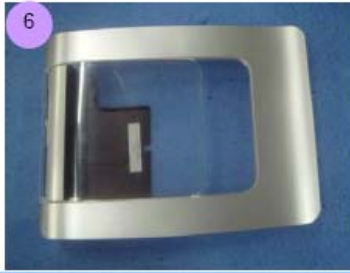
Disassembly IO-clip



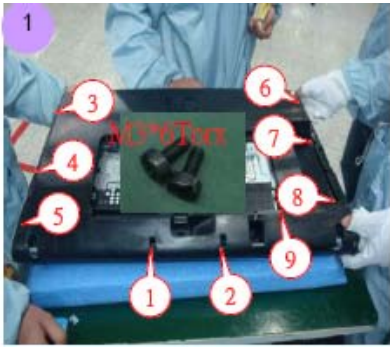
Remove 4 screws on stand



Take the stand out of unit and put it on matrial area



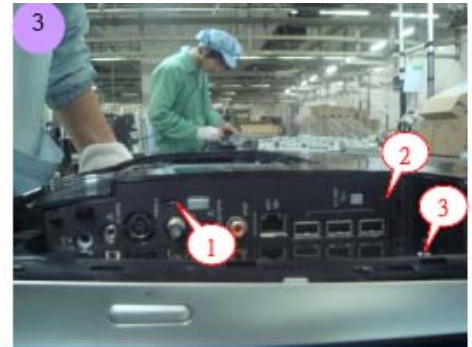
## 6) Rear frame



Remove 8pcs screw on rear cover follow pic order



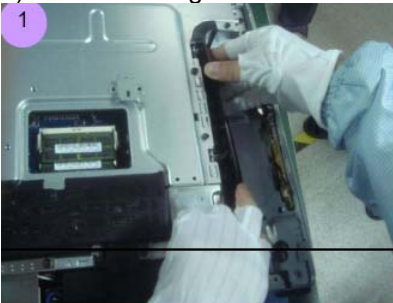
Remove 2 screws in ODD plastic cover and other 3pcs screw on pic shows location



Pull rear cover from unit



## 7) DDR shielding

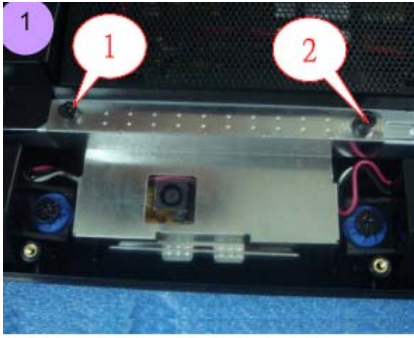


Remove IO Insrt part



Disassemble DDR shielding

### 8) Amp shielding



Dis-lock 2pcs screws on AMP SHIED



Take AMP shield out

### 9) Rear shielding



Disassemble 7pcs screws on rear shielded



Take rear meter shield from chassis



Put rear meter shield on material area

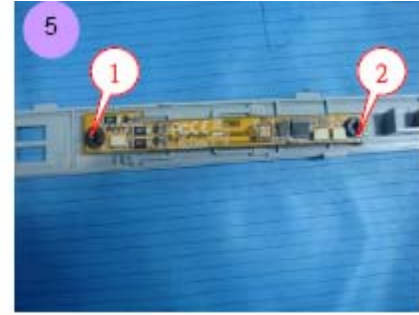
### 10) Side cap



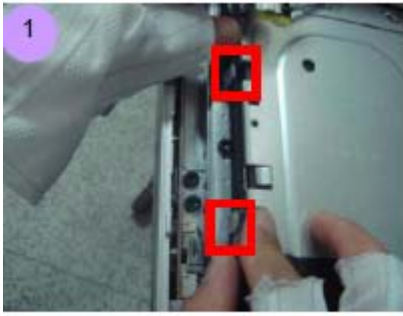
Disassembly right side cap



Plug AMB cable from connector



Dis-lock 2pcs screw on AMB board



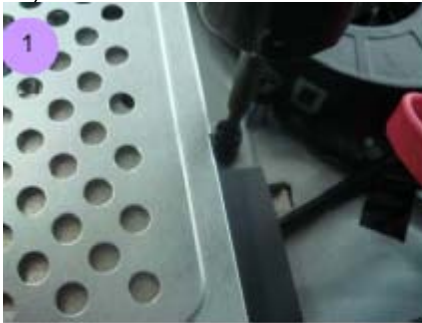
take cable out from hook



Remove left left side cap from chassis and plug power cable from card



### 11) ODD

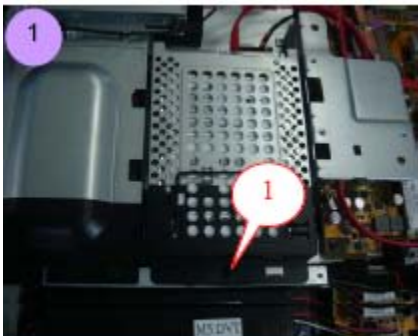


Plug ODD SATA & Power cable from ODD



Dis-lock one pcs screw and take ODD from chassis

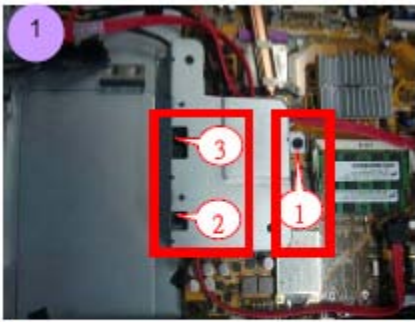
### 12) HDD



Dis-lock HDD screw and take HDD out from unit



Disassemble HDD from HDD cage

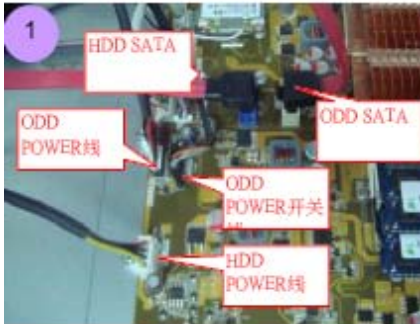


Remove 3pcs screws from HDD BRK

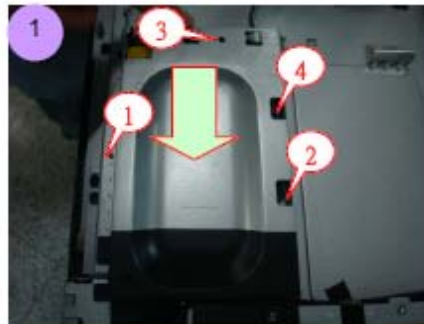


不同型号的螺丝勿混料

13) Some cables and Inverter board cage



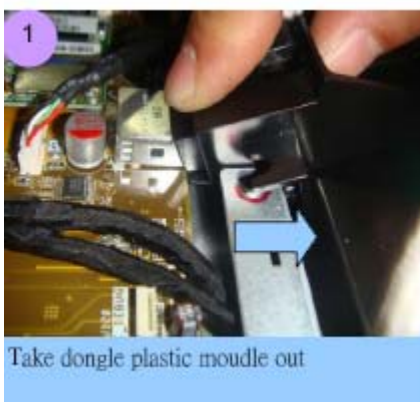
Plug HDD SATA+POWER,ODD SATA+POWER,ODD Eject from MB



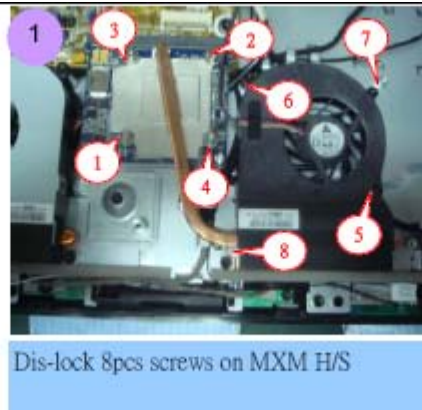
Disassembly inverter brk and pull the brk out hook



14) Thermal module



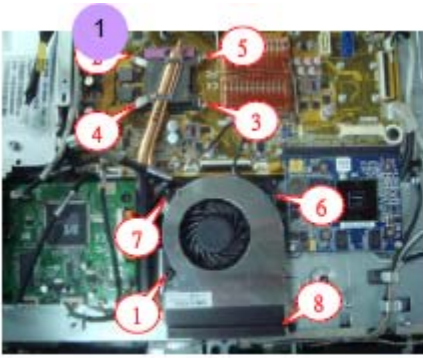
Take dongle plastic module out



Dis-lock 8pcs screws on MXM H/S



Dis-lock 3pcs screw on system fan



Disassemble 7pcs screws from CPU thermal kit as picture



MXM card should lose 2pcs screw to be moved



Disassemble WLAN card from MB



Press the hook and pull the LVDS cable form LCD side



Losse TV card screws and plug out TV card from MB



15) MB and Amp board



Disassemble 5pcs screws on MB and take MB from chassis

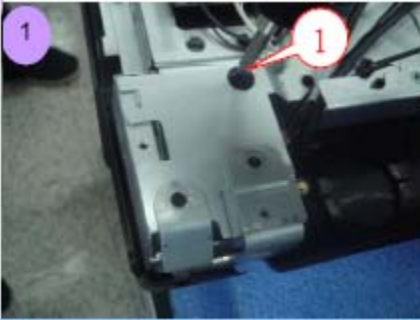


Dis-lock speaker screws



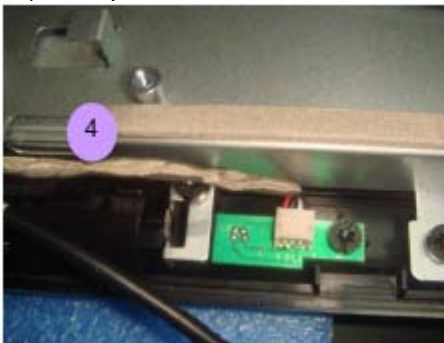
disassembly AMP board

16) CR



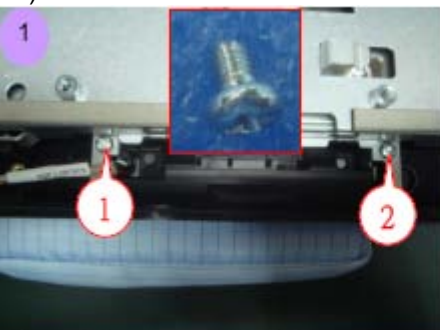
Disassemble Card reader and take it out of card reader shield

17) Microphone



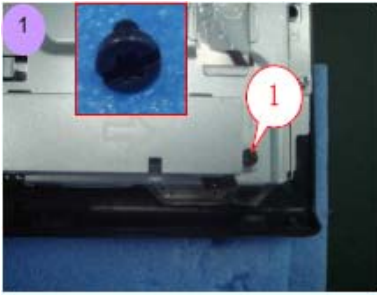
Dis-lock Mic-phone card and take away

18) Webcam

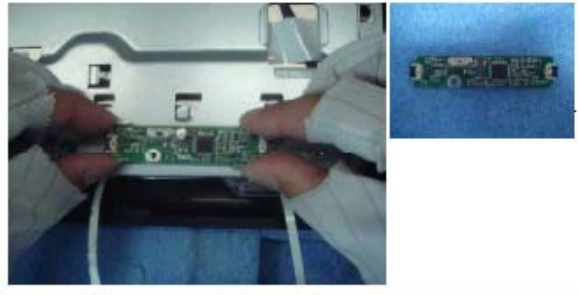


Disassemble camera module kit

19) DSP board

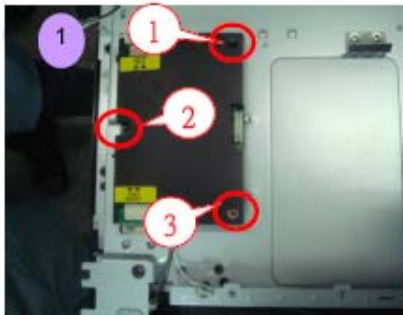


Disassemble DSP cover

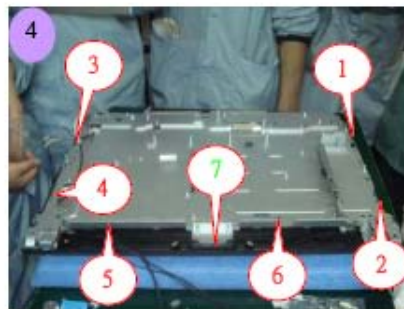


Dis-lock 2pcs screw from DSP board and take out from chassis

20) Inverter board



Disassemble Inverter board



Dis-lock 7pcs screws on base pan from LCD.



Two operators hold base pan, route panel cable from base pan.



Put the units on inspect jig



Figure 2 : Touch panel kit disassembly

## 1) Front bezel



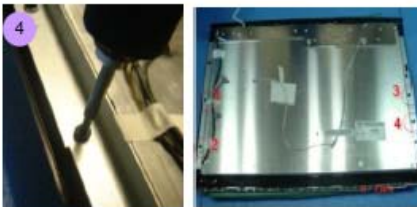
1. Put NG TPK on rotating jig with top side down. Then use static bag to cover FFC cable in order to protect it.



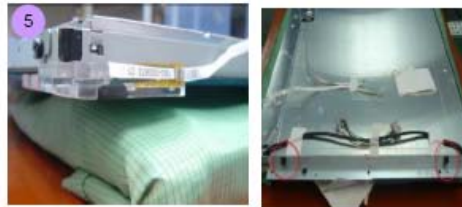
2. Remove acoustic tape which is used for fixing FFC cable from left to right. Then route FFC cable outside of bezel.  
Notice: No damage FFC cable when removing tapes.



3. Remove 4 screws for fixing TOP bracket in turn as pic, then take TOP bracket off.



4. Remove 4 screws for fixing front bezel and R/L bracket in turn. Disassemble bezel and TPK.



5. Put TPK on rotating jig after disassembling it.  
Notice: camera kit needs to hang in the air without any pressure. Then remove screws for locking R/L bracket, take R/L bracket off.

## 2) Camera kit



1. Put TPK upwards and disassemble 4 metal clips with feeler gauge pushed on the edge of metal as the Pic.  
Note : Don't crash camera or scratch camera during the repair process.



2. Power on the hank, set the temperature at 48°C.



3. When the hank temperature reaches 48°C, put TPK in the hank for 15min and make the TPK upwards. Close the hank door and record the time.



4. Put TPK on the ESD foam and out from camera kit bottom(camera 1)(as the left Pic). Move the feeler gauge slowly from the red-line position (please don't separate the top camera kit position.). Then separate camera kit from TPK.  
Note:  
Please don't with much strength when cutting and removing to avoid scratching camera kit and glass.



5. Remove the camera kit from TPK with as the Pic.  
Note : Before removal, make sure the FFC cable free, the strength should be the same during the process, don't touch camera kit or FFC.



6. Remove Camera 2 by the same way as Camera 1.  
Note: Before removal, make sure the FFC cable free, the strength should be the same during the process, don't touch camera kit or FFC.

### 3) Glass



1. Put the TSPK upwards on the table. Cut TSGP from the 30 degree, The cutting depth is 3-5mm



2. Hold the TSGP and cut TSGP from the top to bottom. Pull the knife by 30 degree and the left side of TSGP will be separated.



3. Rotate the TPK 90 degree by contra clock wise. Put knife from the right-top corner and cut the TSGP.



4. Hold the TSGP and cut the bottom side. Pull the knife by 30 degree. The 4 sides for TSGP will all be separated by this way.



5. After making sure all the 4 sides of TPK are all cut, separate TS glass&panel.  
**Note:** Don't pull with much strength or break glass when separating.



6. Compare the Camera Kit S/N with DSP S/N and make sure the S/N are the same.

**Note:** FFC should be protected with ESD bag when putting in the material box as the Pic.

**Figure 3 : Remove molded-in NUT from Chin**

